

subsequent thin film layers so that said semiconductor light receiving element may be adapted to be positioned in place.

16. (amended) A method of fabricating an edge emitting/incidence type semiconductor light receiving element formed by sequentially laminating on a substrate a plurality of different thin film layers including a light absorbing layer, comprising an etching step for eliminating a portion of said light absorbing layer existing at a predetermined region of said light absorbing layer so that said semiconductor light receiving element may be adapted to be positioned in place.

Please cancel claims ~~17-38~~ without prejudice or disclaimer of the subject matter thereof, and add the following new claims:

--39. A light transmitting module comprising:

a substrate;

an optical fiber disposed on one surface of said substrate; and

an edge emitting/incidence type light receiving element HAVING a layer

disposed on said one surface of said substrate;

wherein said layer of said edge emitting/incidence type light receiving element includes a light absorbing portion and another portion which is a non-light absorbing portion and which defines a space region of said layer.

40. A light transmitting module according to claim 39, wherein said light absorbing portion of said layer at least partially surrounds said another portion of said layer which is said non-light absorbing portion and which defines said space region of said layer.

41. A light transmitting module according to claim 39, wherein said edge emitting/incidence type light receiving element is positioned on said one surface of said substrate by projecting a light having a wavelength which is absorbed by said light absorbing portion of said layer and which is enabled to pass said another portion of said layer which is said non-light absorbing portion which defines said space region is enabled to pass.

42. A light transmitting module according to claim 39, wherein said edge emitting/incidence type light receiving element is a semiconductor light receiving element.

43. A light transmitting module according to claim 42, wherein said optical fiber is optically coupled to said semiconductor light receiving element.

44. A light transmitting module according to claim 42, further comprising a semiconductor laser mounted on said substrate, said semiconductor light receiving element being optically coupled to at least one of said semiconductor laser and said optical fiber.

45. A light transmitting module according to claim 43, wherein said semiconductor light receiving element disposed on said substrate is configured by being packaged with either ceramic or resin.

46. A light transmitting module according to claim 44, wherein said semiconductor light receiving element disposed on said substrate is configured by being packaged with either ceramic or resin.--

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